LINEAR TECHNOLOGY MATERIALS DECLARATION

LT1764EFE-2.5#TRPBF **(Engineering Calculation)** TSSOP Exp. Pad

TOTAL MASS (g): **0.07066491**

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COMPONENT MATERIAL	VENDOR/ INDUSTRY NAMES	CONSTITUENT NAME	CAS NUMBER	CONSTITUENT MASS (g)	CONSTITUENT (PPM) OF MATERIAL	CONSTITUENT (PPM) OF TOTAL PKG.
Active Device	Linear Technology	Silicon (Si)	7440-21-3	**0.005437**	**1000000**	**76940.59**
Die Coat	Dow Corning	Silicone	67762-90-7	**0**	**0**	**0**
Lead Frame	Cu	Copper (Cu)	7440-50-8	0.025576	975000	361933.5
		Iron (Fe)	7439-89-6	0.00063	24000	8915.316
		Phosporus (P)	7723-14-0	8E-06	300	113.2104
		Zinc (Zn)	7440-66-6	1.8E-05	700	254.7233
		Nickel (Ni)	7440-02-0	0	0	0
		Silicon (Si)	7440-21-3	0	0	0
		Magnesium (Mg)	7439-95-4	0	0	0
		Tin (Sn)	7440-31-5	0	0	0
		Lead Frame Total:		**0.026232**	**1000000**	**371216.8**
Plating	PMI	Exter. Plating Pb	7439-92-1	0	0	0
		Exter. Plating Sn	7440-31-5	0.00236391	1000000	33452.38
		External Plating Total:		**0.00236391**	**1000000**	**33452.38**
		Inter. Plating Ni	7440-02-0	0	0	0
		Inter. Plating Ag	7440-22-4	0.00103	1000000	14575.83
		Internal Plating Total:		**0.00103**	**1000000**	**14575.83**
Die Attach	ELECTRICALLY CONDUCTIVE ADHESIVE	Silver (Ag)	7440-22-4	0.001372	750000	19415.58
		Tin (Sn)	7440-31-5	0	0	0
		Lead (Pb)	7439-92-1	0	0	0
		Silica (SiO2)	60676-86-0	0	0	0
		Metal Oxide		0	0	0
		Resin (EP)		0.000457	250000	6467.142
		Die Attach Total:		**0.001829**	**1000000**	**25882.72**
Encapsulation	MULTI-AROMATIC RESIN Br/Sb FREE	Resin (EP)		0.004875	150000	68987.56
		Bromine (Br)	40039-93-8	0	0	0
		Silica (SiO2)	60676-86-0	0.02665	820000	377132
		Antimony Trioxide (Sb2O3)	1309-64-4	0	0	0
		Metal Hydroxid		0.000813	25000	11505
		Carbon Black (C)	1333-86-4	0.000163	5000	2306.661
		Encapsulation Total:		**0.032501**	**1000000**	**459931.3**
Bond Wire Estimated	AFW/TANAKA/ Kn	Gold (Au)	7440-57-5	**0.001272**	**1000000**	**18000.45**